

**DECOUPLING CAPACITOR CLOSELY COUPLED
WITH INTEGRATED CIRCUIT**

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Abstract of the Disclosure

An integrated circuit module, decoupling capacitor assembly and method are disclosed. The integrated circuit module includes a substrate and
5 integrated circuit die mounted on the substrate and having die pads and an exposed surface opposite from the substrate. A plurality of substrate bonding pads are positioned on the substrate adjacent the integrated circuit die. A decoupling capacitor assembly is mounted
10 on each integrated circuit die and includes a capacitor carrier secured onto the exposed surface of the integrated circuit die and a decoupling capacitor carried by the capacitor carrier. A wire bond extends from the decoupling capacitor assembly to a die pad and from a die
15 pad to a substrate bonding pad.